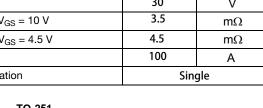


N-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS}	30	V			
R _{DS(on)} V _{GS} = 10 V	3.5	mΩ			
$R_{DS(on)}$ $V_{GS} = 4.5 \text{ V}$	4.5	mΩ			
I_{D}	100	Α			
Configuration	Sino	gle			



FEATURES

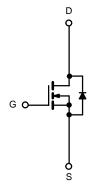
- TrenchFET® Power MOSFET
- 100 % $\rm R_{\rm g}$ and UIS Tested Compliant to RoHS Directive 2011/65/EU



COMPLIANT

APPLICATIONS

- OR-ing
- Server
- DC/DC



N-Channel MOSFET

10-251					
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(G	D		s	
	Тор	٧	iew	/	

ABSOLUTE MAXIMUM RATINGS	S (T _A = 25 °C, unle	ss otherwise not	ted)	
Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V _{DS}	30	V
Gate-Source Voltage		V _{GS}	± 20	
	T _C = 25 °C		100 ^{a, e}	
Continuous Drain Current (T _{.I} = 175 °C)	T _C = 70 °C		95 ^e	
Continuous Diam Current (1, = 175 C)	T _A = 25 °C	I _D	35 ^{b, c}	A
	T _A = 70 °C		26 ^{b, c}	^
Pulsed Drain Current		I _{DM}	197	
Avalanche Current Pulse	L = 0.1 mH	I _{AS}	39	
Single Pulse Avalanche Energy	L = 0.1 IIII	E _{AS}	94.8	mJ
Continuous Source-Drain Diode Current	T _C = 25 °C	I.	90 ^{a, e}	А
	T _A = 25 °C	l _s —	3.13 ^{b, c}	☐ ^
	T _C = 25 °C		250 ^a	
Maximum Power Dissipation	T _C = 70 °C	ь	175	10/
	T _A = 25 °C	P _D	3.75 ^{b, c}	W
	T _A = 70 °C		2.63 ^{b, c}	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 175	°C

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Тур.	Max.	Unit	
Maximum Junction-to-Ambient ^{b, d}	t ≤ 10 sec	R _{thJA}	32	40	°C/W	
Maximum Junction-to-Case	Steady State	R _{thJC}	0.5	0.6	C/VV	

Notes:

- a. Based on T_C = 25 °C.
 b. Surface mounted on 1" x 1" FR4 board.

- b. Striate informed on 1 X 1 114 board.
 c. t = 10 sec.
 d. Maximum under steady state conditions is 90 °C/W.
 e. Calculated based on maximum junction temperature. Package limitation current is 90 A.



SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)						
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static				1	ı	
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V, I}_{D} = 250 \mu\text{A}$	30			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = 250 μA		35		mV/°C
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_{J}$			- 7.5		111 7 0
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	1.0		2.5	V
Gate-Source Leakage	I_{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
Zero Gate Voltage Drain Current	l- a-a	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$	1		1	
Zero Gate Voltage Drain Gurrent	IDSS	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$			10	μΑ
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	90			Α
	D	V _{GS} = 10 V, I _D = 38.8 A		3.5		m()
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 37 \text{ A}$		4.5		mΩ
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 38.8 A		160		S
Dynamic ^b						
Input Capacitance	C _{iss}			3000		pF
Output Capacitance	C _{oss}	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		710		
Reverse Transfer Capacitance	C _{rss}			170		
Total Oats Ohanna	0	V _{DS} = 15 V, V _{GS} = 10 V, I _D = 38.8 A		170		
Total Gate Charge	Q_g	V _{DS} = 15 V, V _{GS} = 4.5 V, I _D = 28.8 A		81.5		nC
Gate-Source Charge	Q _{gs}			34		
Gate-Drain Charge	Q_{gd}			29		
Gate Resistance	R _g	f = 1 MHz		1.4	2.1	Ω
Turn-On Delay Time	t _{d(on)}			18	27	
Rise Time	t _r	$V_{DD} = 15 \text{ V}, R_{L} = 0.625 \Omega$		11	17	
Turn-Off Delay Time	t _{d(off)}	$I_D\cong 24$ A, V_{GEN} = 10 V, R_g = 1 Ω		70	105	
Fall Time	t _f			10	15	
Turn-On Delay Time	t _{d(on)}			55	83	ns
Rise Time	t _r	$V_{DD} = 15 \text{ V}, R_{L} = 0.67 \Omega$		180	270	-
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 22.5 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		55	83	
Fall Time	t _f	, , , , , , , , , , , , , , , , , , ,		12	18	1
Drain-Source Body Diode Characteristic	:S				I 	
Continuous Source-Drain Diode Current	Is	T _C = 25 °C			120	
Pulse Diode Forward Current ^a	I _{SM}				120	A
Body Diode Voltage	V _{SD}	I _S = 22 A		0.8	1.2	V
Body Diode Reverse Recovery Time	t _{rr}			52	78	ns
Body Diode Reverse Recovery Charge	Q _{rr}			70.2	105	nC
Reverse Recovery Fall Time	t _a	$I_F = 20 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		27		
Reverse Recovery Rise Time	t _b			25		ns

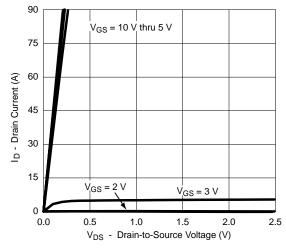
Notes:

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

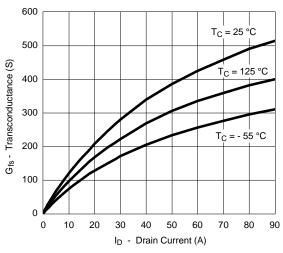
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



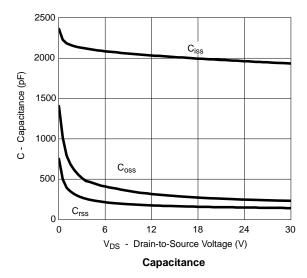
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

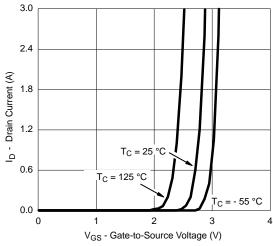


Output Characteristics

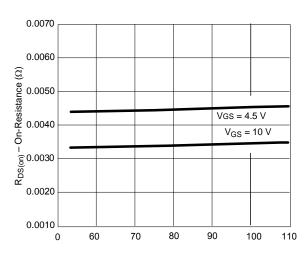


Transconductance

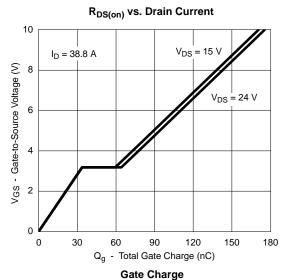




Transfer Characteristics



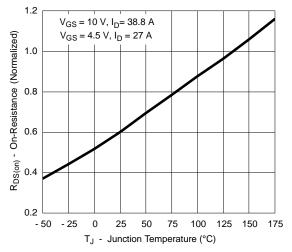
I_D - Drain Current (A)



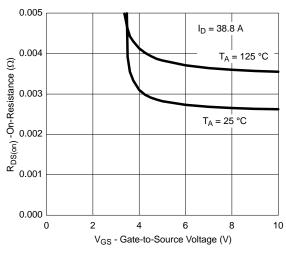
3



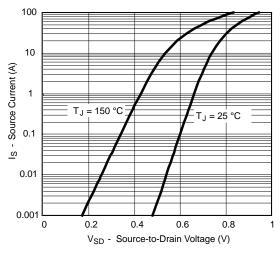
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



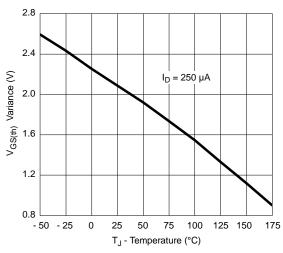
On-Resistance vs. Junction Temperature



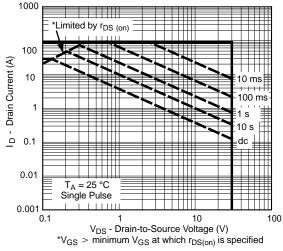
 $R_{DS(on)}\, vs.\, V_{GS}\, vs.\, Temperature$



Forward Diode Voltage vs. Temperature



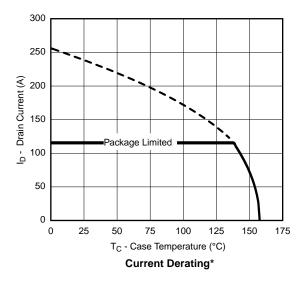
Threshold Voltage

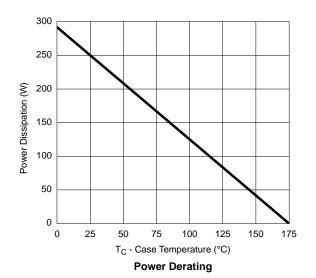


Safe Operating Area, Junction-to-Ambient

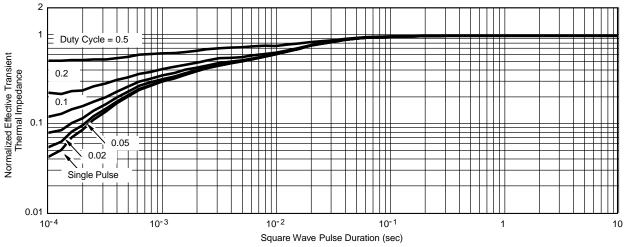


TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





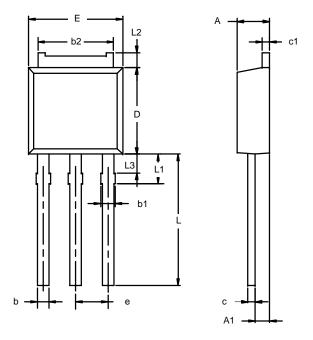
*The power dissipation P_D is based on $T_{J(max)}$ = 175 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



Normalized Thermal Transient Impedance, Junction-to-Case



TO-251AA (DPAK)



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	MILLIM	IETERS	INCHES		
Dim	Min	Max	Min	Max	
Α	2.21	2.38	0.087	0.094	
A1	0.89	1.14	0.035	0.045	
b	0.71	0.89	0.028	0.035	
b1	0.76	1.14	0.030	0.045	
b2	5.23	5.43	0.206	0.214	
С	0.46	0.58	0.018	0.023	
с1	0.46	0.58	0.018	0.023	
D	5.97	6.22	0.235	0.245	
E	6.48	6.73	0.255	0.265	
е	2.28	BSC	0.090 BSC		
L	8.89	9.53	0.350	0.375	
L1	1.91	2.28	0.075	0.090	
L2	0.89	1.27	0.035	0.050	
L3	1.15	1.52	0.045	0.060	
ECN: S-03946—Rev. E, 09-Jul-01 DWG: 5346					

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